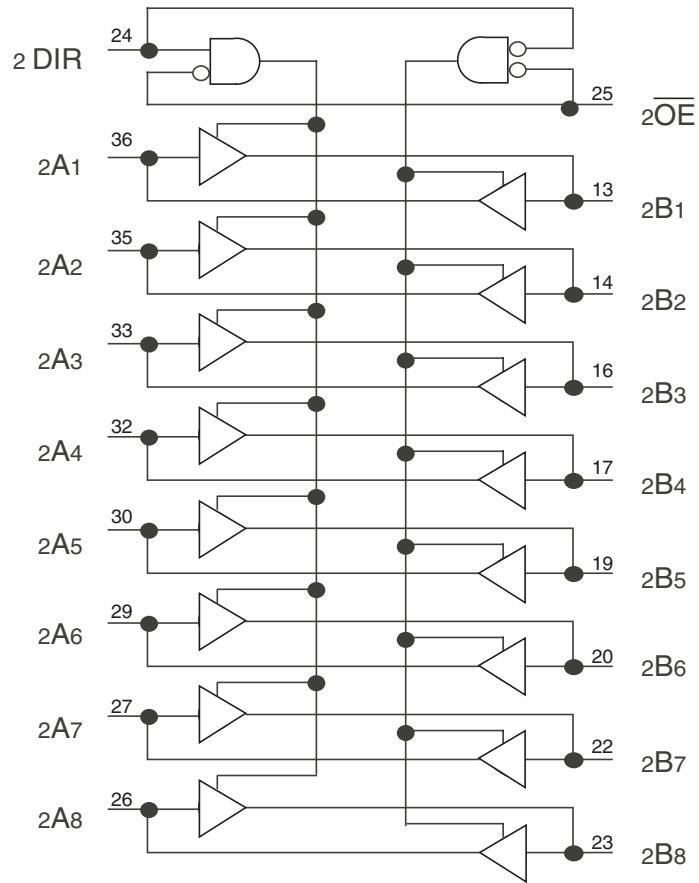
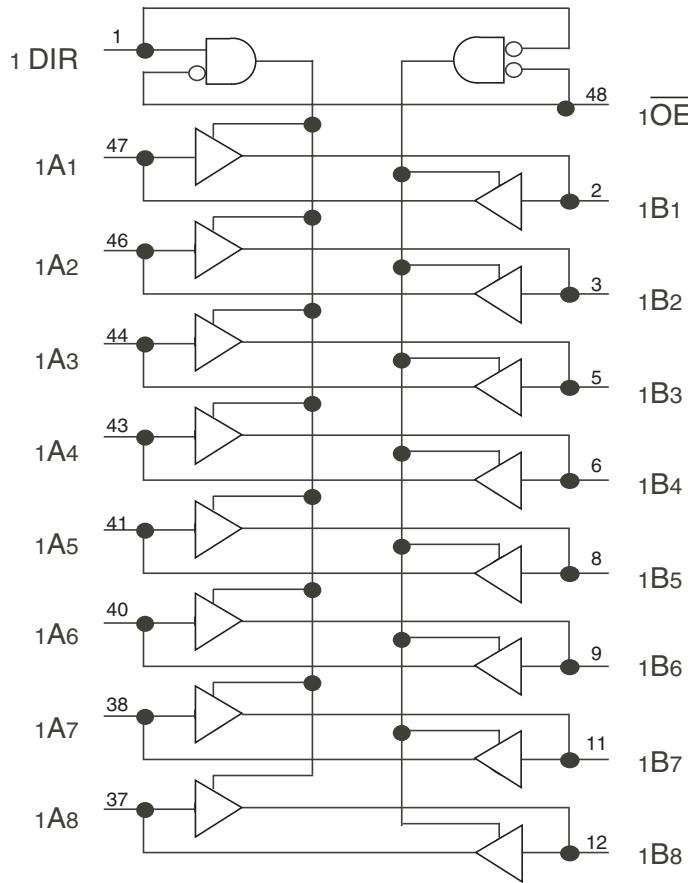


FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{sk(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{cc} = 3.3V \pm 0.3V$, Normal Range, or $V_{cc} = 2.7V$ to $3.6V$, Extended Range
- CMOS power levels (0.4 μ W typ. static)
- Rail-to-rail output swing for increased noise margin
- Low Ground Bounce (0.3V typ.)
- Inputs (except I/O) can be driven by 3.3V or 5V components
- Available in SSOP, TSSOP, and TVSOP packages

DESCRIPTION:

The FCT163245 16-bit transceivers are built using advanced dual metal CMOS technology. These high-speed, low-power transceivers are ideal for asynchronous communication between two buses (A and B). The Direction and Output Enable controls are designed to operate these devices as either two independent 8-bit transceivers or one 16-bit transceiver. The direction control pin (xDIR) controls the direction of data flow. The output enable pin (xOE) overrides the direction control and disables both ports. All inputs are designed with hysteresis for improved noise margin.

FUNCTIONAL BLOCK DIAGRAM

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INDUSTRIAL TEMPERATURE RANGE

PIN CONFIGURATION

1DIR		1	48		1OE
1B1		2	47		1A1
1B2		3	46		1A2
GND		4	45		GND
1B3		5	44		1A3
1B4		6	43		1A4
VCC		7	42		VCC
1B5		8	41		1A5
1B6		9	40		1A6
GND		10	39		GND
1B7		11	38		1A7
1B8		12	37		1A8
2B1		13	36		2A1
2B2		14	35		2A2
GND		15	34		GND
2B3		16	33		2A3
2B4		17	32		2A4
VCC		18	31		VCC
2B5		19	30		2A5
2B6		20	29		2A6
GND		21	28		GND
2B7		22	27		2A7
2B8		23	26		2A8
2DIR		24	25		2OE

SSOP/ TSSOP/ TVSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to 7	V
VTERM ⁽⁴⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +60	mA

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Vcc terminals.
3. Input terminals.
4. Outputs and I/O terminals.

CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
COUT	Output Capacitance	VOUT = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
xOE ₁	Output Enable Input (Active LOW)
xDIR	Direction Control Input
xAx	Side A Inputs or 3-State Outputs
xBx	Side B Inputs or 3-State Outputs

FUNCTION TABLE⁽¹⁾

Inputs		Outputs
xOE ₁	xDIR	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

NOTE:

1. H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Don't Care
- Z = High-impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = 2.7V to 3.6V

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level		2	—	5.5	V
	Input HIGH Level (I/O pins)			2	—	VCC+0.5	
VIL	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level		-0.5	—	0.8	V
I _{IH}	Input HIGH Current (Input pins)	VCC = Max.	VI = 5.5V	—	—	±1	μA
	Input HIGH Current (I/O pins)		VI = VCC	—	—	±1	
I _{IL}	Input LOW Current (Input pins)		VI = GND	—	—	±1	
	Input LOW Current (I/O pins)		VI = GND	—	—	±1	
I _{OZH}	High Impedance Output Current	VCC = Max.	VO = VCC	—	—	±1	μA
I _{OZL}	(3-State Output pins)		VO = GND	—	—	±1	
V _{IK}	Clamp Diode Voltage	VCC = Min., I _{IN} = -18mA		—	-0.7	-1.2	V
I _{ODH}	Output HIGH Current	VCC = 3.3V, VIN = VIH or VIL, VO = 1.5V ⁽³⁾		-36	-60	-110	mA
I _{ODL}	Output LOW Current	VCC = 3.3V, VIN = VIH or VIL, VO = 1.5V ⁽³⁾		50	90	200	mA
V _{OH}	Output HIGH Voltage	VCC = Min.	I _{OH} = -0.1mA	VCC-0.2	—	—	V
		VIN = VIH or VIL	I _{OH} = -3mA	2.4	3	—	
		VCC = 3V	I _{OH} = -8mA	2.4 ⁽⁵⁾	3	—	
V _{OL}	Output LOW Voltage	VCC = Min.	I _{OL} = 0.1mA	—	—	0.2	V
		VIN = VIH or VIL	I _{OL} = 16mA	—	0.2	0.4	
		VCC = 3V	I _{OL} = 24mA	—	0.3	0.55	
		VIN = VIH or VIL	I _{OL} = 24mA	—	0.3	0.5	
I _{OS}	Short Circuit Current ⁽⁴⁾	VCC = Max., VO = GND ⁽³⁾		-60	-135	-240	mA
V _H	Input Hysteresis	—		—	150	—	mV
I _{CCL} I _{CCH} I _{CCZ}	Quiescent Power Supply Current	VCC = Max. VIN = GND or VCC		—	0.1	10	μA

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at VCC = 3.3V, +25°C ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. This parameter is guaranteed but not tested.
5. V_{OH} = VCC-0.6V at rated current.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V _{CC} = Max. V _{IN} = V _{CC} - 0.6V ⁽³⁾		—	2	30	μA
I _{CCD}	Dynamic Power Supply Current ⁽⁴⁾	V _{CC} = Max. Outputs Open x _{OE} = x _{DIR} = GND One Input Toggling 50% Duty Cycle	V _{IN} = V _{CC} V _{IN} = GND	—	50	75	μA/ MHz
I _C	Total Power Supply Current ⁽⁶⁾	V _{CC} = Max., Outputs Open f _I = 10MHz 50% Duty Cycle x _{OE} = x _{DIR} = GND One Bit Toggling	V _{IN} = V _{CC} V _{IN} = GND	—	0.5	0.8	mA
		V _{IN} = V _{CC} - 0.6V V _{IN} = GND	—	0.5	0.8		
		V _{IN} = V _{CC} V _{IN} = GND	—	2	3 ⁽⁵⁾		
		V _{IN} = V _{CC} - 0.6V V _{IN} = GND	—	2	3.3 ⁽⁵⁾		

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at V_{CC} = 3.3V, +25°C ambient.

3. Per TTL driven input. All other inputs at V_{CC} or GND.

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP}/2 + f_I N_I)$

I_{CC} = Quiescent Current (I_{CC1}, I_{CC2} and I_{CC3})

ΔI_{CC} = Power Supply Current for a TTL High Input

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current caused by an Input Transition Pair (HLH or LHL)

f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)

N_{CP} = Number of Clock Inputs at f_{CP}

f_I = Input Frequency

N_I = Number of Inputs at f_I

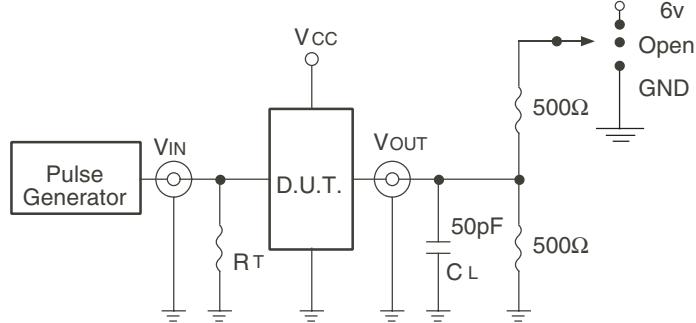
SWITCHING CHARACTERISTICS OVER OPERATING RANGE⁽¹⁾

Symbol	Parameter	Condition ⁽²⁾	FCT163245A		FCT163245C		Unit
			Min. ⁽³⁾	Max.	Min. ⁽³⁾	Max.	
t _{PLH}	Propagation Delay A to B, B to A	C _L = 50pF R _L = 500Ω	1.5	4.6	1.5	4.1	ns
t _{PHL}			1.5	6.2	1.5	5.8	ns
t _{PZH}	Output Enable Time xO _E to A or B		1.5	5	1.5	4.8	ns
t _{PZL}	Output Disable Time xO _E to A or B		1.5	6.2	1.5	5.8	ns
t _{PZH}	Output Enable Time xDIR to A or B ⁽⁴⁾		1.5	5	1.5	4.8	ns
t _{PZL}	Output Disable Time xDIR to A or B ⁽⁴⁾		—	0.5	—	0.5	ns
tsk(0)	Output Skew ⁽⁵⁾						

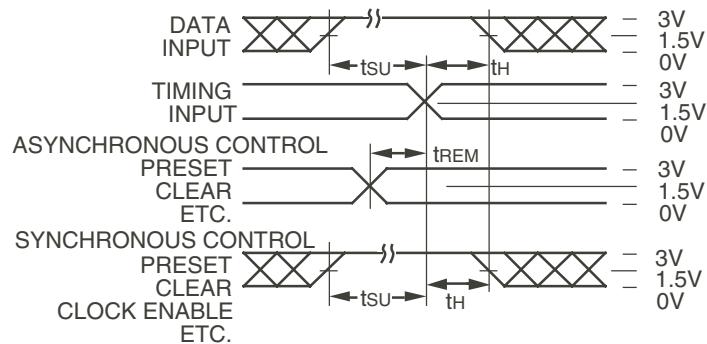
NOTES:

1. Propagation Delays and Enable/Disable times are with V_{CC} = 3.3V ±0.3V, Normal Range. For V_{CC} = 2.7V to 3.6V, Extended Range, all Propagation Delays and Enable/Disable times should be degraded by 20%.
2. See test circuit and waveforms.
3. Minimum limits are guaranteed but not tested on Propagation Delays.
4. This parameter is guaranteed but not tested.
5. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.

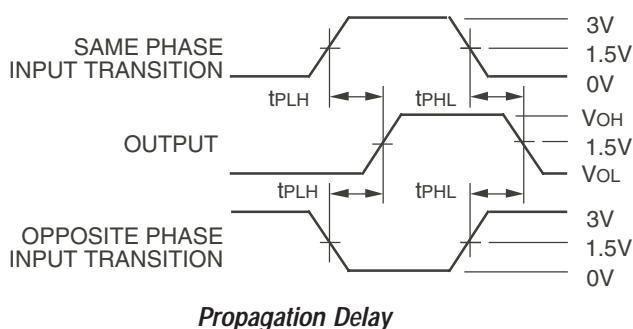
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



Propagation Delay

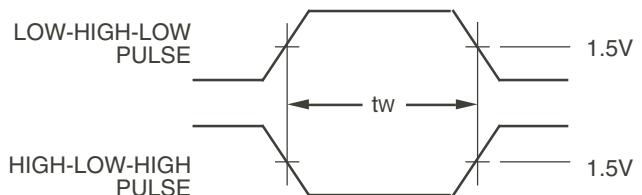
SWITCH POSITION

Test	Switch
Open Drain	6V
Disable Low	GND
Enable Low	Open
Disable High	GND
Enable High	Open
All Other Tests	Open

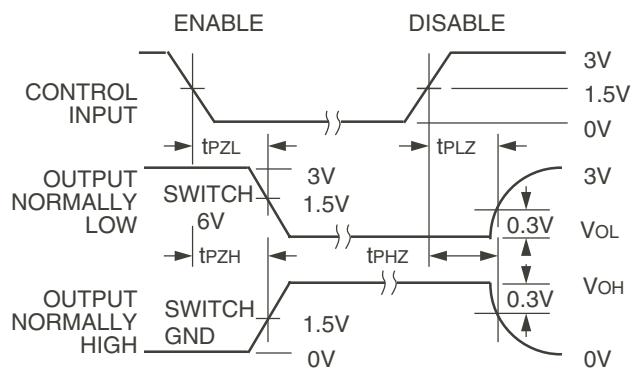
DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



Pulse Width



Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_f \leq 2.5\text{ns}$; $t_r \leq 2.5\text{ns}$.
3. If V_{CC} is below 3V, input voltage swings should be adjusted not to exceed V_{CC} .

ORDERING INFORMATION

XX	FCT	XXX	XXXX	X	
Temp. Range	Family		Device Type	Package	
				PVG PAG PFG	Shrink Small Outline Package - Green Thin Shrink Small Outline Package - Green Thin Very Small Outline Package - Green
				245A 245C	Non-Inverting 16-Bit Bidirectional Transceiver
				163	Double-Density 3.3Volt
				74	– 40°C to +85°C

Datasheet Document History

09/10/09 Pg.7 Updated the ordering information by removing the "IDT" notation and non RoHS part.

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